

Single P-Channel MOSFET

■ DESCRIPTION

SMC3401G is the P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced trench technology devices are well suited for high efficiency fast switching applications, low in-line power loss needed in small outline surface mount package.

■ PART NUMBER INFORMATION

SMC 3401G SN - TR G

a	b	c	d	e
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a : Company name.

b : Product Serial number.

c : Package code SN: SOT-23

d : Handling code TR: Tape&Reel

e : Green produce code G: *RoHS Compliant*

■ FEATURES

$$V_{DS} = -30V, \quad I_D = -3.8A$$

$$R_{DS(ON)}=54m\Omega(Typ.)@V_{GS}=-10V$$

$$R_{DS(ON)}=64m\Omega(Typ.)@V_{GS}=-4.5V$$

$$R_{DS(ON)}=83m\Omega(Typ.)@V_{GS}=-2.5V$$

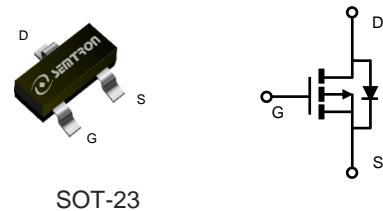
◆Fast switch

◆2.5V Low gate drive applications

■ APPLICATIONS

◆Portable Equipment

◆Power Management



SOT-23

■ ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ Unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-Source Voltage	-30	V
V_{GSS}	Gate-Source Voltage	± 12	V
I_D	Continuous Drain Current	$T_A=25^\circ C$	-3.8
		$T_A=70^\circ C$	-3.0
I_{DM}	Pulsed Drain Current ^A	-15.2	A
P_D	Power Dissipation ^B	$T_A=25^\circ C$	1.3
		$T_A=70^\circ C$	0.8
T_J	Operation Junction Temperature	-55/150	$^\circ C$
T_{STG}	Storage Temperature Range	-55/150	$^\circ C$

■ THERMAL RESISTANCE

Symbol	Parameter	Typ	Max	Units
$R_{\theta JA}$	Thermal Resistance Junction to Ambient ^B	$t \leq 10s$	95	$^\circ C/W$
	Thermal Resistance Junction to Ambient ^{BC}	Steady-State	130	

ELECTRICAL CHARACTERISTICS($T_A = 25^\circ\text{C}$ Unless otherwise noted)

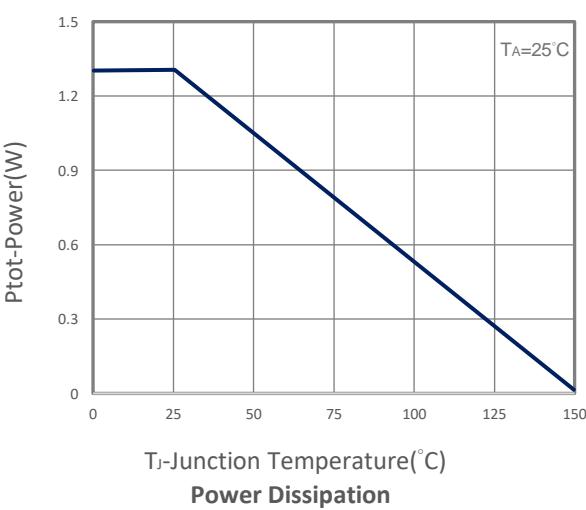
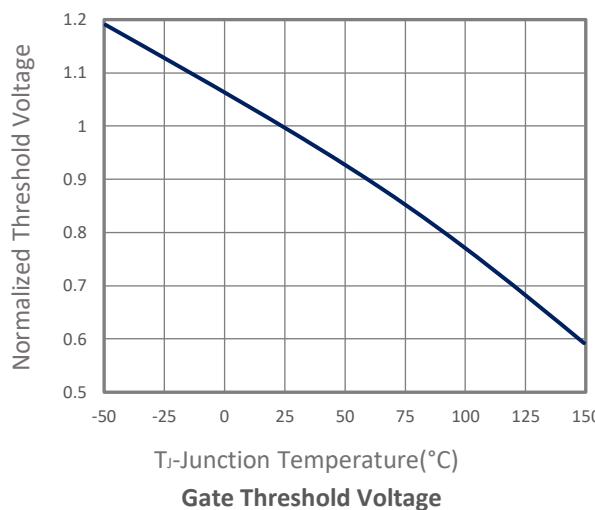
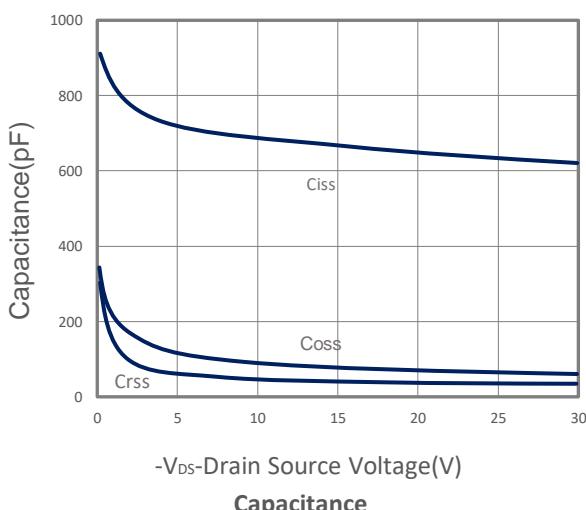
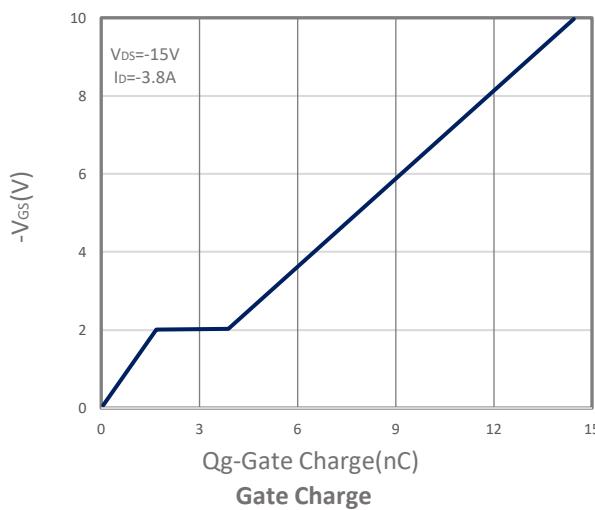
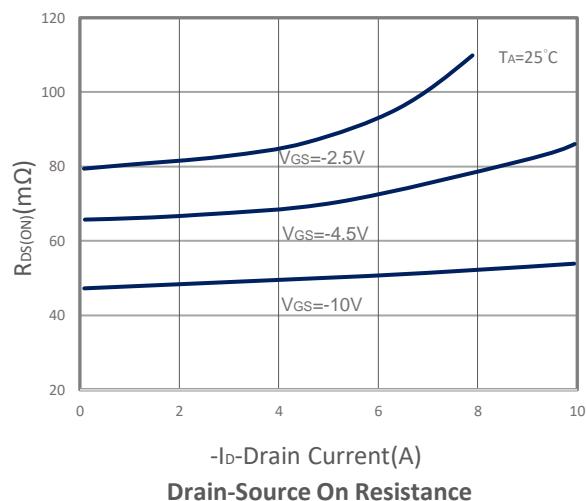
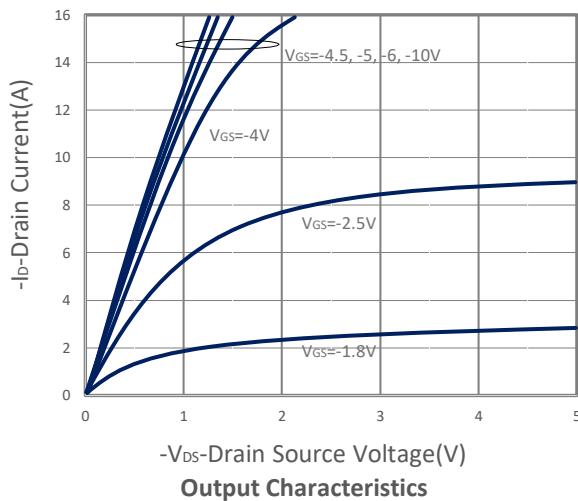
Symbol	Parameter	Condition	Min	Typ	Max	Unit	
Static Parameters							
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=-250\mu\text{A}$	-30			V	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=-250\mu\text{A}$	-0.5	-0.7	-1	V	
I_{GSS}	Gate Leakage Current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 12\text{V}$			± 100	nA	
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-30\text{V}$, $V_{GS}=0\text{V}$, $T_J=25^\circ\text{C}$			-1	μA	
		$V_{DS}=-24\text{V}$, $V_{GS}=0\text{V}$, $T_J=75^\circ\text{C}$			-10		
$R_{DS(\text{ON})}$	Drain-source On-Resistance	$V_{GS}=-10\text{V}$, $I_D=-3.8\text{A}$		54	60	$\text{m}\Omega$	
		$V_{GS}=-4.5\text{V}$, $I_D=-3.2\text{A}$		64	75		
		$V_{GS}=-2.5\text{V}$, $I_D=-2.2\text{A}$		83	95		
G_f	Forward Transconductance	$V_{DS}=-10\text{V}$, $I_D=-3.8\text{A}$		15		S	
Diode Characteristics							
V_{SD}	Diode Forward Voltage	$I_S=-1\text{A}$, $V_{GS}=0\text{V}$		-0.7	-1	V	
I_S	Continuous Source Current				-1.9	A	
Dynamic and Switching Parameters							
$Q_g(10\text{V})$	Total Gate Charge	$V_{DS}=-15\text{V}$, $V_{GS}=-10\text{V}$ $I_D=-3.8\text{A}$		14.5	20	nC	
$Q_g(4.5\text{V})$	Total Gate Charge			7	9.8		
Q_{gs}	Gate-Source Charge			1.55	2.2		
Q_{gd}	Gate-Drain Charge			2	2.8		
C_{iss}	Input Capacitance	$V_{DS}=-15\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$		630		pF	
C_{oss}	Output Capacitance			71			
C_{rss}	Reverse Transfer Capacitance			42			
$t_{d(on)}$	Turn-On Time	$V_{DD}=-15\text{V}$, $V_{GEN}=-10\text{V}$, $R_G=6\Omega$, $I_D=1\text{A}$		4.8	9	nS	
t_r				8.2	16		
$t_{d(off)}$	Turn-Off Time			36	68		
t_f				9.6	18		

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

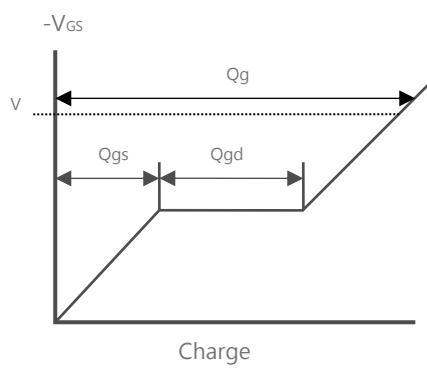
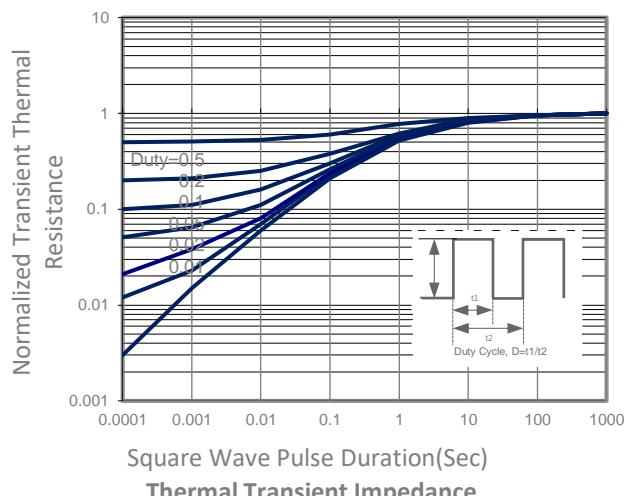
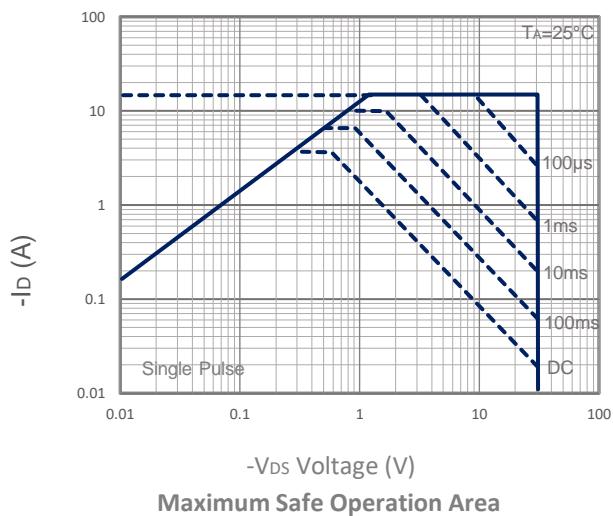
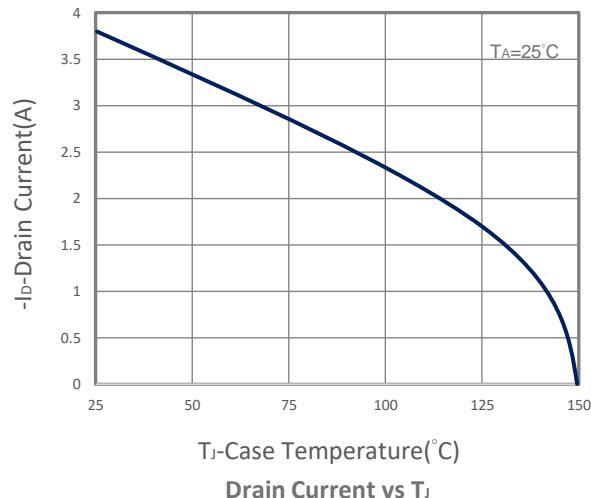
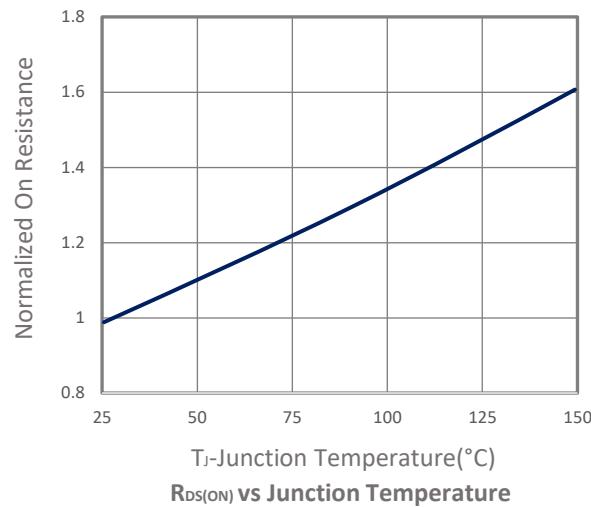
- A. Pulsed width limited by maximum junction temperature, $T_J(\text{MAX})=150^\circ\text{C}$.
- B. Measure the value in a still air environment at $T_A=25^\circ\text{C}$, using an installation mounted on a 1 in2 FR-4 board, maximum junction temperature $T_J(\text{MAX})=150^\circ\text{C}$.
- C. $T_J(\text{MAX})=150^\circ\text{C}$, using junction-to-case thermal resistance (R_{ojc}) is more useful in additional heat sinking is used.

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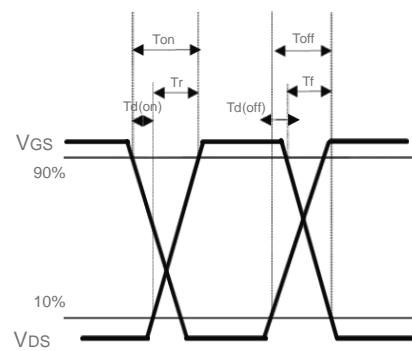
TYPICAL CHARACTERISTICS



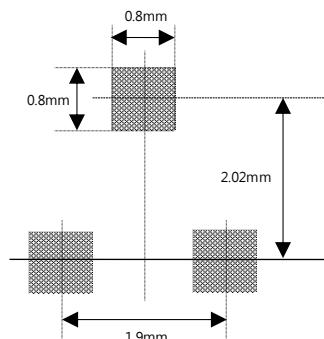
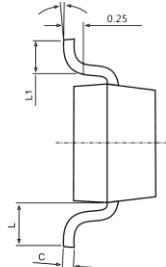
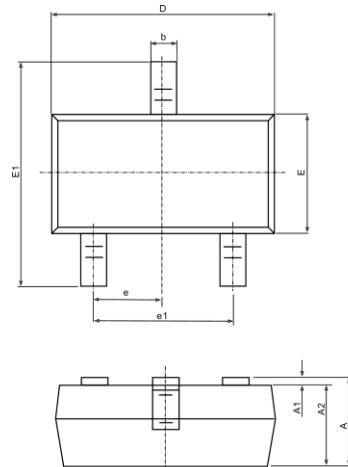
TYPICAL CHARACTERISTICS



Gate Charge Waveform



Switching Time Waveform

SOT-23 PACKAGE DIMENSIONS


Recommended Land Pattern

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°